



SOT972-2

plastic, thermal enhanced extremely thin small outline
package; no leads; 8 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN1714-8
Package type industry code	DFN1714-8
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	2-8-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.6	-	1.7	1.8	mm
E	package width	1.25	-	1.35	1.45	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	8	-	



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2. Package outline

DFN1714-8: plastic, thermal enhanced extremely thin small outline package; no leads; 8 terminals; body 1.35 x 1.7 x 0.5 mm

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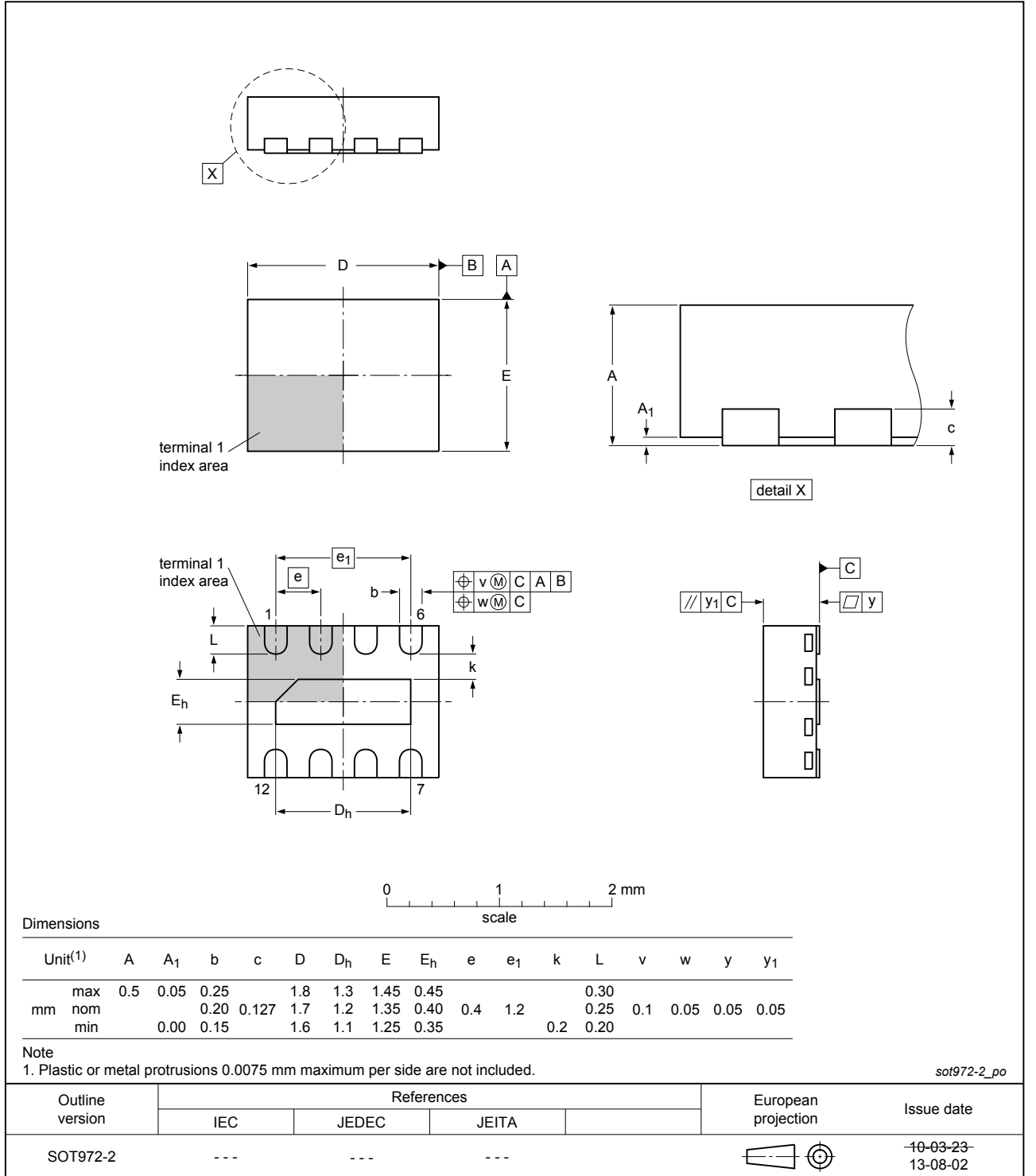


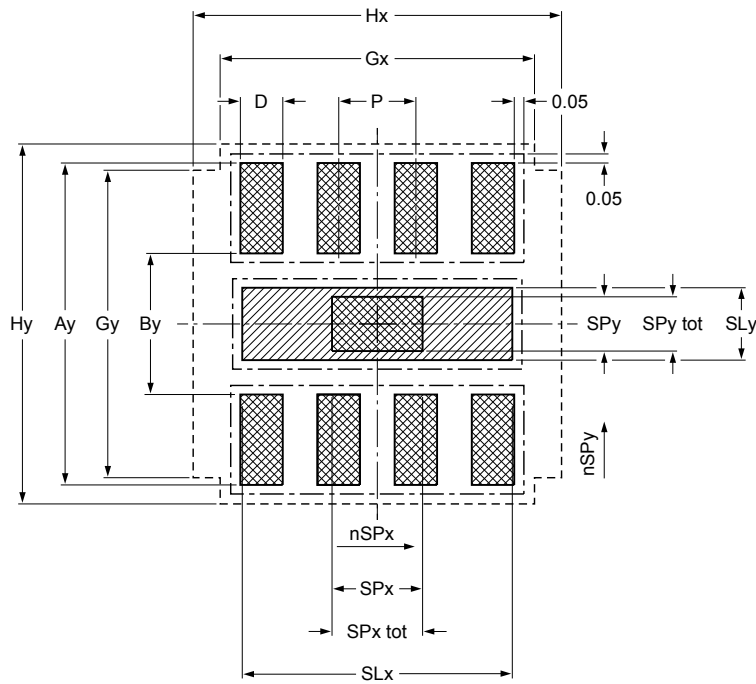
Fig. 1. Package outline DFN1714-8 (SOT972-2)

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

3. Soldering

Footprint information for reflow soldering of DFN1714-8 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist

DIMENSIONS in mm

P	Ay	By	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy	nSPx	nSPy
0.400	1.780	0.780	0.220	1.400	0.400	0.500	0.300	0.500	0.300	1.630	1.700	1.910	1.990	1	1

Issue date ~~12-08-28~~
13-08-02

sot972-2_fr

Fig. 2. Reflow soldering footprint for DFN1714-8 (SOT972-2)

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4. Legal information

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